



## SHORT BIO

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**Prof. Seung-Boo Jung** received his Ph.D. from Osaka University, Japan in 1993 and joined KIST in 1994. He has been working at the Department of Advanced Materials Engineering, Sungkyunkwan University, Korea since 1995.

Professor Jung published more than 500 peer reviewed papers related to micro-bonding of dissimilar materials and semiconductor packaging in international journals. He holds more than 50 patents and his research has been cited more than 15,000 times. He served as the President of the Korea Microelectronics Packaging Society (KMEPS) and the President of the Korea Microelectronics Packaging Society (KAMP) in 2018 and 2021.

Recently, he has been interested in advanced electronic package technology for carbon neutrality.